Guidelines taken from IPC-7351

Library Expert Footprint Naming Convention

PCB Libraries, Inc.

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Surface Mount Land Pattern Naming Convention

	BGA + Pin Qty. + C or N + P Pitch _ Ball Columns X Ball Rows _ Body Length X Width X Height + B Ball Diameter
	n Qty. + C or N + P Col Pitch X Row Pitch Ball Columns X Ball Rows Body Length X Width X Height + B Ball Diameter BGAS + Pin Qty. + C or N + P Pitch Ball Columns X Ball Rows Body Length X Width X Height + B Ball Diameter
	CAPCAF + Pin Qty. + P Pitch _ + Body Length X Width X Height + L Lead Length X Width
Capacitors, Chip	
	CAPPC + Body Length X Width X Height + L Lead Length
	CAPDFN + Body Length X Width X Height + L Lead Length X Width
	CAPAE + Base Body Size X Height + L Lead Length X Width
Ceramic Flat Packages	
	CGA + Pin Qty. P Pitch _ Pin Columns X Pin Rows _ Body Length X Width X Height + L Diameter
	XTAL + Body Length X Width X Height + L Lead Length X WidthXTALDFN + Body Length X Width X Height + L Lead Length X Width
	XTALSC + Body Length X Width X Height + L Lead Length
	DIOC + Body Length X Width X Height + L Lead Length
	DIODFN + Pin Qty Body Length X Width X Height + L Lead Length X Width
	DIOM + Lead Span X Body Width X Height + L Lead Length X Width
	DIONC + Lead Span X Body Width X Height + L Lead Length
	DIONDFN + Pin Qty Body Length X Width X Height + L Lead Length X Width DIONM + Lead Span X Body Width X Height + L Lead Length X Width
	DIOMELF + Body Length + Diameter + L Lead Length
	DIOSC Body Length X Width X Height + L Lead Length
Diodes, Side Concave, 4 Pin	DIOSC4 + P Pitch Body Length X Width X Height + L Lead Length
	SODFL + Lead Span X Body Width X Height + L Lead Length X Width
	DPAK + Pin Qty. + P Pitch _ Lead Span X Height + L Lead Length X Width + T Thermal Tab Pad Length X Width
	FUSC + Body Length X Width X Height + L Lead Length
	FUSM + Lead Span X Body Width X Height + L Lead Length X Lead Width
Fuses, Side Concave	FUSSC + Body Length X Width X Height + L Lead Length
IC, Small Outline Package, Flat Lead	
	INDDFN + Body Length X Width X Height + L Lead Length X Width
Inductors, Molded	INDM + Lead Span X Body Width X Height + L Lead Length X Width
	INDSC + Body Length X Width X Height + L Lead Length
	LGA + Pin Qty. + C + P Pitch _ Pin Columns X Pin Rows _ Body Length X Width X Height + L Lead Diameter
Land Grid Array, Circular Lead	LGA + Pin Qty. + S + P Pitch _ Pin Columns X Pin Rows _ Body Length X Width X Height + L Lead Size
	LEDC + Body Length + Width X Height + L Lead Length
	LEDDFN + Body Length X Width X Height + L Lead Length X Width
	LEDM + Lead Span X Body Width X Height + L Lead Length X Width
	LEDSC + Body Length X Width X Height + L Lead Length
	LEDSC4 + P Pitch _ Body Length X Width X Height + L Lead LengthOSCDFN4 _ Body Length X Width X Height + L Lead Length X Width
	OSCSC + Pin Qty. + P Pitch Body Length X Width X Height + L Lead Length X Width
	OSCSF + Pin Qty. + P Pitch Body Length X Width X Height + L Lead Length X Width
	OSCJ + Pin Qty. + P Pitch _ Body Length X Lead Span X Height + L Lead Width
	OSCL + Pin Qty. + P Pitch Body Length X Lead Span X Height + L Lead Length X Width
	PLCC + Pin Qty. + P Pitch _ Lead Span L1 X Lead Span L2 Nominal X Height + L Lead WidthPLCCS + Pin Qty. + P Pitch _ Lead Span L1 X Lead Span L2 Nominal X Height + L Lead Width
	PSON + Pin Qty. + P Pitch _ Body Length X Width X Height + L Lead Length X Width + T Thermal Pad Length X Width
	PQFN + Pin Qty. + P Pitch Body Length X Width X Height + L Lead Length X Width + T Thermal Pad Length X Width
	r. + P Pitch _ Lead Span L1 X Lead Span L2 Nominal X Height + L Lead Length X Width + T Thermal Pad Length X Width
	CQFP + Pin Qty. + P Pitch _ Lead Span L1 X Lead Span L2 Nominal X Height + L Lead Length X Width
	QFN + Pin Qty. + P Pitch _ Body Length X Width X Height + L Lead Length X Width + T Thermal Pad Length X Width
Quad Leadless Ceramic Chip Carriers (Pin 1 on Side)	LCC + Pin Qty. + P Pitch _ Body Length X Width X Height + L Lead Length X WidthLCCS + Pin Qty. + P Pitch _ Body Length X Width X Height + L Lead Length X Width
Resistors. Chip	RESC + Body Length X Width X Height + L Lead Width
Resistors, Chip, Array, Concave	RESCAV + Pin Qty. + P Pitch Body Length X Width X Height + L Lead Length X Width
Resistors, Chip. Array, Convex, E-Version (Even Pin Size)	
Resistors, Chip, Array, Convex, S-Version (Side Pins Diff)	
Resistors, Chip, Array, Flat	RESCAF + Pin Qty. + P Pitch Body Length X Width X Height + L Lead Length X Width
Resistors, Dual Flat No-lead	
Resistors Molded	RESM + Lead Span X Body Width X Height + L Lead Length X Width
	RESSC + Body Length X Width X Height + L Lead Length X Width
Small Outline IC, J-Leaded	SOJ + Pin Qty. + P Pitch _ Body Length X Lead Span X Height + L Lead Width
	Pin Qty. + P Pitch _ Body Length X Lead Span X Body Height + L Lead Length X Width + T Thermal Pad Length X WidthSON + Pin Qty. + P Pitch _ Body Length X Width X Height + L Lead Length X Width + T Thermal Pad Length X Width
	SON + Pin Qty. + P Pitch _ Body Length X Width X Height + L Lead Length X Width + T Thermal Pad Length X Width
	SOT143- + Pin Qty. + P Pitch _ Lead Span X Body Height + L Lead Length
SOT343	SOT343- + Pin Qty. + P Pitch _ Lead Span X Body Height + L Lead Length
	SOT23- + Pin Qty. + P Pitch _ Lead Span X Body Height + L Lead Length
	SOT223- + Pin Qty. + P Pitch _ Lead Span X Body Height + L Lead Length
	THRMC + Body Length + Width X Height + L Lead Width TRXSOFL + Pin Qty. + P Pitch + Lead Span X Body Length X Body Height + L Lead Length X Width
	TRXBOFL + Pin Qty. + P Picti _ + Lead Span X Body Length X Body Height + L Lead Length X Width
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Library Expert Naming Convention for Through-Hole Land Patterns

The land pattern naming convention uses component dimensions to derive the land pattern name.

The first 3 – 6 characters in the land pattern name describe the component family.

The first number in the land pattern name refers to the Lead Spacing or hole to hole location to insert the component lead.

All numbers that follow the Lead Spacing are component dimensions.

These characters are used as component body identifiers that precede the value and this is the priority order of the component body identifiers – **P** = Pitch for components with more than two leads

W = Maximum Lead Width (or Component Lead Diameter)

L = Body Length for horizontal mounting

D = Body Diameter for round component body

T = Body Thickness for rectangular component body

H = Height for vertically mounted components

Q = Pin Quantity for components with more than two leads

R = Number of Rows for connectors

Notes

All component body values are in millimeters and go two places to the right of the decimal point and no leading zeros.

All Complexity Levels used in the examples are "B".

Component, Category Land Pattern Name Capacitors, Non Polarized Axial Diameter Horizontal Mounting....... CAPAD + Lead Spacing + W Lead Width + L Body Length + D Body Diameter Example: CAPAD800W52L600D150 Capacitors, Non Polarized Axial Diameter; Lead Spacing 8.00; Lead Width 0.52; Body Length 6.00; Body Diameter 1.50 Capacitors, Non Polarized Axial RectangularCAPAR + Lead Spacing + W Lead Width + L Body Length + T Body thickness + H Body Height Example: CAPAR800W52L600T50H70 Capacitors, Non Polarized Axial; Lead Spacing 8.00; Lead Width 0.52; Body Length 6.00; Body Thickness 0.50; Body Height 0.70 Capacitors, Non Polarized Axial Diameter Vertical Mounting CAPADV + Lead Spacing + W Lead Width + L Body Length + D Body Diameter Example: CAPADV300W52L600D150 Capacitors, Non Polarized Axial; Lead Spacing 3.00; Lead Width 0.52; Body Length 6.00; Body Diameter 1.50mm Capacitors, Non Polarized Axial Rect. Vert. Mtg. CAPARV + Lead Spacing + W Lead Width + L Body Length + T Body Thickness + H Body Height Example: CAPARV300W52L600T50H70 Capacitors, Non Polarized Axial Rect. Vertical; Lead Spacing 8.00; Lead Width 0.52; Body Length 6.00; Body Thickness 0.50; Body Height 0.70 Capacitors, Non Polarized Radial Diameter......CAPRD + Lead Spacing + W Lead Width + D Body Diameter + H Body Height Example: CAPRD200W52D300H550 Capacitors, Non Polarized Radial Diameter; lead spacing 2.00; lead width 0.52; Body Diameter 3.00; Height 5.50 Capacitors, Non Polarized Radial Rectangular CAPRR + Lead Spacing + W Lead Width + L Body Length + T Body thickness + H Body Height Example: CAPRR200W52L50T70H550 Capacitors, Non Polarized Radial Rectangular; lead spacing 2.00; lead width 0.52; Body Length 0.50; Body thickness 0.70; Height 5.50 Capacitors, Non Polarized Radial Disk Button.......CAPRB + Lead Spacing + W Lead Width + L Body Length + T Body thickness + H Body Height Example: **CAPRB200W52L50T70H550** Capacitors, Non Polarized Radial Rectangular; lead spacing 2.00; lead width 0.52; Body Length 0.50; Body thickness 0.70; Height 5.50 Example: CAPPAD800W52L600D150 Capacitors, Polarized Axial Diameter, Lead Spacing 8.00; Lead Width 0.52; Body Length 6.00; Body Diameter 1.50 Capacitor, Polarized Radial Diameter CAPPRD + Lead Spacing + W Lead Width + D Body Diameter + H Body Height Example: CAPPRD200W52D300H550 Capacitors, Polarized Radial Diameter; lead spacing 2.00; lead width 0.52; Body Diameter 3.00; Height 5.50 Diodes, Axial Diameter Horizontal Mounting......DIOAD + Lead Spacing + W Lead Width + L Body Length + D Body Diameter Example: DIOAD800W52L600D150 Diodes, Non Polarized Axial Diameter; Lead Spacing 8.00; Lead Width 0.52; Body Length 6.00; Body Diameter 1.50 Example: DIOADV300W52L600D150 Diodes, Non Polarized Axial; Lead Spacing 8.00; Lead Width 0.52; Body Length 6.00; Body Diameter 1.50 Dual-In-Line PackagesDIP + Lead Span + W Lead Width + P Pin Pitch + L Body Length + H Component Height + Q Pin Qty Example: DIP762W52P254L1905H508Q14 Dual-In-Line Package: Lead Span 7.62; Lead Width 0.52; Pin Pitch 2.54; Body Length 19.05; Body Height 5.08; Pin Qty 14 Dual-In-Line Sockets.....DIPS + Lead Span + W Lead Width + P Pin Pitch + L Body Length + H Component Height + Q Pin Qty Example: DIPS762W52P254L1905H508Q14 Dual-In-Line Package Socket: Lead Span 7.62; Lead Width 0.52; Pin Pitch 2.54; Body Length 19.05; Body Height 5.08; Pin Qty 14

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Headers. Vertical.......HDRV + Lead Span + W Lead Width + P Pin Pitch + R Pins per Row + L Body Length + T Body Thickness + H Height
Example: HDRV200W52P200R2L4400T400H900
Header, Vertical: Lead Span 2.00; Lead Width 0.52; Pin Pitch 2.00; 2 Rows; Body Length 44.00; Body Thickness 4.00; Body Height 9.00
Headers, Right Angle ...... HDRRA + Lead Span + W Lead Width + P Pin Pitch + R Pins per Row + L Body Length + T Body Thickness + H Height
Example: HDRRA200W52P200R2L4400T400H900
Header, Vertical: Lead Span 2.00; Lead Width 0.52; Pin Pitch 2.00; 2 Rows; Body Length 44.00; Body Thickness 4.00; Body Height 9.00
Inductors, Axial Diameter Horizontal Mounting......INDAD + Lead Spacing + W Lead Width + L Body Length + D Body Diameter
Example: INDAD800W52L600D150
Inductors, Axial Diameter; Lead Spacing 8.00; Lead Width 0.52; Body Length 6.00; Body Diameter 1.50
Inductors, Axial Diameter Vertical Mounting ......INDADV + Lead Spacing + W Lead Width + L Body Length + D Body Diameter
Example: INDADV300W52L600D150
Inductors, Axial Diameter Vertical Mounting; Lead Spacing 3.00; Lead Width 0.52; Body Length 6.00; Body Diameter 1.50
Inductors, Non-Polarized, Radial Diameter ......INDRD + Lead Spacing + W Lead Width + D Body Diameter + H Body Height
Example: INDRD800W52D600H500
Inductors, Non-Polarized, Radial Diameter; Lead Spacing 8.00: Lead Width 0.52; Body Diameter 6.00; Body Height 5.00
Inductors, Polarized, Radial Diameter + H Body Height
Example: INDPRD300W52D600H500
Inductors, Polarized, Radial Diameter; Lead Spacing 3.00; Lead Width 0.52; Body Diameter 6.00; Body Height 5.00
Example: JUMP500W52
Jumper; Lead Spacing 5.00; Lead Width 0.52
Example: MTGP700H400Z520
This is a Mounting hole for a #6-32 screw using a circular 7.00 land on the primary and secondary side of the board, a 4.00 diameter hole with the
internal lands are smaller that the external and are also circular 5.20 in diameter.
Example: MTGNP700H400Z520
This is a Mounting hole for a #6-32 screw using a circular 7.00 land on the primary and secondary side of the board, a 4.00 diameter hole with the
internal lands are smaller that the external and are also circular 5.20 in diameter.
Mounting Holes Non-Plated Without Support Pad ......MTGNP + Pad Size + H Hole Size + Z Inner Layer Pad Size + K Keep-out Diameter
Example: MTGNP100H400Z520K700
This is a Mounting hole for a #6-32 screw using a circular 1mm land on the primary and secondary side of the board, a 4.00 diameter hole with the
internal lands are smaller that the external and are also circular 5.20 in diameter and a 7.00 diameter keep-out.
Example: MTGP700H400Z520V8
This is a Mounting hole for a #6-32 screw using a circular 7mm land on the primary and secondary side of the board, a 4mm diameter hole with the
internal lands are smaller that the external and are also circular 5.2mm in diameter, with 8 vias.
Example: PGA84P254C10R10L2500X2500H300
Pin Grid Array: Pin Qty 84; Pin Pitch 2.54; Columns 10; Rows 10; Body Length 25.00 X 25.00; Component Height 3.00
Resistors, Axial Diameter Horizontal Mounting......RESAD + Lead Spacing + W Lead Width + L Body Length + D Body Diameter
Example: RESAD800W52L600D150
Resistors, Axial Diameter; Lead Spacing 8.00; Lead Width 0.52; Body Length 6.00; Body Diameter 1.50
Example: RESADV300W52L600D150
Resistors, Axial Diameter Vertical Mounting; Lead Spacing 3.00; Lead Width 0.52; Body Length 6.00; Body Diameter 1.50
Resistors, Axial Rectangular Horizontal Mounting .. RESAR + Lead Spacing + W Lead Width + L Body Length + T Body thickness + H Body Height
Example: RESAR800W52L600T50H70
Resistors, Axial Rectangular; Lead Spacing 8.00; Lead Width 0.52; Body Length 6.00; Body Thickness 0.50; Body Height 0.70
Single-In-Line Packages......SIP + Body Width + W Lead Width + P Pin Pitch + L Body Length + H Component Height + Q Pin Qty
Example: DIP150W52P254L1905H508Q14
Single-In-Line Package: Body Width 1.5; Lead Width 0.52; Pin Pitch 2.54; Body Length 19.05; Body Height 5.08; Pin Qty 14
Example: TP52
Example: TPS52
Example: TPRS52
Example: PAD52
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Library Expert Land Pattern Naming Convention Notes

- All dimensions are in Metric Units
- All Lead Span and Height numbers go two places past the decimal point and "include" trailing Zeros
- All Lead Span and Body Sizes go two place before the decimal point and "remove" leading Zeros
- All Chip Component Body Sizes are one place to each side of the decimal point
- · Pitch Values are two places to the right & left of decimal point with no leading Zeros but include trailing zeros

Land Pattern Naming Convention: Each land pattern in IPC-7351 is specified by a unique name that must convey the package family type, pin quantity, pin pitch, body length and width dimensions, terminal lead span, terminal lead length and width and thermal pad dimensions whenever applicable. Other fields in a land pattern name are optional and are discussed below.

Table 1 specifies the naming convention for each package type. The following notes provide the user with guidance on using the table.

Specific characters are reserved for use in the naming convention to denote or separate certain fields:

- P: Prefixes pin pitch. For example, P80 specifies a 0.80 mm pitch between terminations.
- L: Prefixes nominal lead dimensions
- T: Prefixes thermal tab dimensions
- X: Dimension separator. For example, 0.80 mm by 1.50 mm is denoted 80X150
- C, N: Denote Collapsing and Non-collapsing balls respectively when specifying a BGA land pattern
- _: Underscore is a field separator between pin quantity and/or pin pitch and the package body dimensions
- -: Dash is a field separator between pin quantity in hidden and deleted pin components
- +: Plus denotes "in addition to". The plus "+" symbol does not actually appear in the land pattern name but is only used to assist the user in reading Table 1.

Additional notes for using Table 1:

- All dimensions are metric units
- All dimensions are nominal except height is maximum
- All numeric values are two places before and after the decimal point and "remove" leading Zeros
- If there is no pin quantity in the Land Pattern Name it is assumed that the pin quantity is 2
- Thermal Tabs are included in the Pin Quantity

Additional and Optional Fields:

The suffix letters "L", "M", and "N" are used to signify when the land protrusion is at their minimum (least), maximum (most), or median (nominal) protrusion and appear as the last character. The 3 Density Levels are defined as follows:

M = Maximum (Most) Material Condition (Density Level A)

N = Median (Nominal) Material Condition (Density Level B)

L = Minimum (Least) Material Condition (Density Level C)

If no Density Level suffix is provided, then the land pattern either follows the component manufacturer's recommended pattern or a custom land pattern for use with multiple component manufacturer's packages in the same component family.

Additional suffices for JEDEC Standard parts that have several alternate packages are as follows:

AA, AB, AC JEDEC Component Identifier (used primarily on Semiconductor packages).

Additional suffixes for alternate components that do not follow the JEDEC standard are as follows (these are located before the Density Level suffix):

"A" – Alternate Component letter is used when component package nominal dimensions are the same for two packages but the package tolerances are different enough to create a unique land pattern to avoid land pattern name duplication.

Ball Grid Array (BGA) packages may require land pattern names that indicate a difference in pitch between balls in the rows vs. balls in the columns. These are often referred to as a "dual pitch BGA". For example, the BGA land pattern name of BGA48C**80X100**P6X8_900X1200X120 conveys that the pitch 0.80 mm between columns and 0.100 mm between rows.

Note: In this example, Pin A1 is assumed to be located in the Lower left when viewing the package from the top view. A 90° rotation of the BGA swaps the definition of Rows and Columns.

A pin order or pin quantity modifier shall be added to the component package type specification to convey reverse pin ordering, hidden pins, or deleted pins.

SOP20R: 20 pin part, Reverse Pin Order

SOT143R: Reverse Pin Order

SOP20-24: 20 pin part in a 24 pin package. The pins are numbered 1 - 24 the hidden pins are skipped over. The schematic symbol displays up to 24 pins.

SOP24-20: 20 pin part in a 24 pin package. The pins are numbered 1-20 the deleted pins are removed. The schematic symbol displays 20 pins.

Land Pattern Naming for Non-conforming Packages: A large number of component packages are unique, non-standard packages or unique connectors. These component packages do not fit into a standard land pattern name due to their unique features. Therefore, in order to have a single land pat tern naming convention that covers every component package in the electronics industry, the land pattern name must be associated with the component manufacturer and their part number or case code as shown below:

ManufacturerNameAbbreviation_ManufacturerPartNumber or ManufacturerNameAbbreviation_ManufacturerCaseCode

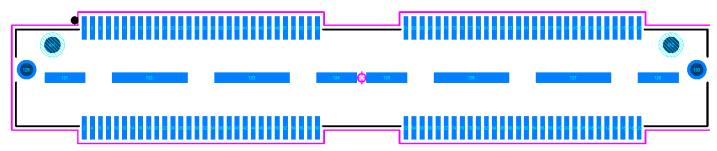
- All special characters used in the part number will be replaced with a hyphen "-" except periods "." will be replaced with an underscore " ".
- If the component package or connector is unique and has a single manufacturer part number, then Part Number would be used to generate the Land Pattern Name
- The component is a standard package and is associated with multiple manufacturer part numbers then manufacturer Case Code would be used to generate the Land Pattern Name

Examples:

FOXCONN_JFM38U1A-2PVT-4F MOLEX_67503-1020 SAMTEC_QTH-060-01-L-D-A TI_RKG41 MAXIM_L1053-H2 CUI SJ-3566AN CK_CRD16CM0SB ABRACON_ABM11 AMPHENOL_101-00565-64

For reference, various unique footprints are shown below that are non-conforming with Table 1.

SAMTEC_QTH-060-01-L-D-A - SMT Connector with plated mounting and non-plated alignment holes



Appendix I - Library Expert Manufacturer Names for updates, visit <u>www.PCBLibraries.com/downloads</u>

3M	3M	BH Electronics	BHELECTRONICS
4D	4D	Binder	
Aavid Thermalloy	AAVID	Bivar	BIVAR
Abracon	ABRACON	BLOCK	BLOCK
Active-Semi	ACTIVESEMI	Blockmaster Electronics	BLOCKMASTER
Adafruit	ADAFRUIT	Bluegiga Technologies	BLUEGIGA
Adam Technologies	ADAMTECH	Bosch-Sensortec	
Adesto Technologies	ADESTO	Bothhand	BOTHHAND
Advanced	ADVANCED	Bourns	BOURNS
Advanced Acoustic Technology	AAT	BrightKing	BRIGHTKING
Advanced Crystal Technology	ADVCRYSTAL	Broadcom	BROADCOM
Advanced Linear Devices		Buddies Technology	BUDDIES
AEL Crystals		Bulgin	BULGIN
Aeroflex	AEROFLEX	C&K	CK
AirBorn	AIRBORN	C3Semi	C3
AKM Semiconductor	AKMSEMI	Caddock	CADDOCK
Akros Silicon	AKROS	Cal-Chip	CALCHIP
Allegro Micro	ALLEGRO	California Eastern Laboratories	CEL
Alliance Memory	ALLIANCE	Cambion	CAMBION
Allwinner Technology	ALLWINNER	Cambridge Silicon Radio	CSR
Alpha & Omega	ALPHA	Camden Boss	CAMDEN
Alpha Novatech		Cantherm	CANTHERM
Alps		Cardinal	CARDINAL
Altech	ALTECH	Carling Technologies	CARLING
Altera	ALTERA	Central	
Amazing Microelectronic	AMAZINGMICRO	Challenge Electronics	CHALLENGE
Ambiq Micro		Changjiang Connectors	CJT
American Electrical		Chequers Electronic	
American Technical Ceramics	AMTECHCER	ChinaSound	CHINASOUND
Ametherm	AMETHERM	Cinch	CINCH
Amgis Toroids	AMGIS	Cirrus Logic	CIRRUS
Amotech	AMOTECH	Citizen Finedevice	CITIZEN
Amphenol	AMPHENOL	Cliff Electronic Components	CLIFF
Amphenol Advanced Sensors	AMPHENOLAS	CnC Tech	CNCTECH
Amphenol Aerospace Operations	AMPHENOLAE	COEV Magnetics	COEVMAG
Amphenol Canada	AMPHENOLCA	CogniMem Technologies	COGNIMEM
Amphenol Connex		Coilcraft	COILCRAFT
Amphenol ICC	AMPHENOLICC	Coilmaster	COILMASTER
ams AG	AMSAG	Comax Electronics	
Amtek Technology	AMTEK	Comchip	COMCHIP
Analog Devices	ANALOG	COMM CON Connectors	COMMCON
Anaren		CONEC	
Andon	ANDON	Conexant	CONEXANT
Anglia	ANGLIA	Connor-Winfield	CONNORWINFIELD
Antenova	ANTENOVA	Contact Technology	CONTACT
Apacer Technology	APACER	Copal	COPAL
Apem		Cornell Dubilier Electronics	CDE
Apex Microtechnology	APEXMICRO	Cosel	COSEL
API Delevan		Cotex Industrial	COTEX
API Technologies		Coto	COTO
Aquantia	AQUANTIA	Cree	CREE
Arch Electronics	ARCHELEC	Crystek	CRYSTEK
Aries	ARIES	CS Bright	CSBRIGHT
Artesyn Embedded Technologies	ARTESYN	CTC Coils	CTCCOILS
ASJ	ASJ	CTS	
Assmann	ASSMANN	CUI	
Atmel		Custom MMIC	CUSTOMMMIC
AUK Contractors		CviLux	
Avago Technologies		CW Industries	
Avdel		Cyntec	
AVX	AVX	Cypress Semiconductor	
Azimuth Electronics		Cyrod	
AzureWave		Darfon Electronics	
Battery Space	BATTERYSPACE	Data Delay Devices	DATADELAY
Bel Power Solutions		Datatronics	DATATRONICS
BelFuse	BELFUSE	Davicom	DAVICOM
Bellwether	BELLWETHER	Decawave	DECAWAVE

Defense Supply Center, Columbus	DSC	Freebird Semiconductor	FREEBIRDSEMI
Degson Electronics		Freescale	
Delta Electronics		Fremont Micro Devices	FMD
Deltron		Fresco Logic	FRESCO
Device Engineering		Frontier	
Dialight		FTDI Chip	
Dialog		Fuji	
Dielectric		Fujitsu	
DIGI		Fuzetec	
Digilent		GAIA Converter	
Digitron Semiconductors		GaN Systems	
Dinkle		General Electric	
Diodes		GeneSiC	
Dionics		Geyer Electronic	
Diotec Semiconductor		Glenair	
DIPTRONICS		Global Connector Technology	
Dominant Semiconductors DORJI Applied Technologies		Golledge Gowanda	
DYNAMAX		GradConn	
EastRising Technology		Grayhill	
Eaton Bussmann		Greenliant	
EBY Electro		GSI Technology	
Ecliptek		HAHN	
ECS International		Haiiwai Electronics	
EDAC		HALO Electronics	
EECO		Hamamatsu	
Efficient Power Conversion		HanRun	
Electrocube		HAOYU Electronics	
Electronic Assembly		Harting	
Elesta		Hartmann	
Elite Semiconductor Memory Technology	ESMT	Harvatek	HARVATEK
ELMA		Harwin	HARWIN
Elmo Motion Control	ELMO	Hewlett Packard	HP
Elna	ELNA	Hillcrest Labs	HILLCRESTLABS
EMC Technology	EMCTECH	Hirose	HIROSE
EnOcean	ENOCEAN	Hittite	HITTITE
Enpirion	ENPIRION	HK Resistors	HKRESISTORS
Enpirion	ENPIRION	HMicro	HMICRO
Envoy Data		Holt	
EPCOS	EPCOS	Holtek Semiconductor	HOLTEK
Epitex		Holy Stone	
Epson		Honda Tsushin Kogyo	
ERNI		Honeywell	
ESKA		Hongfa	
Espressif		Hoyato	
E-Switch		HUBER+SUHNER	
E-tec Interconnect		IC Plus	
Etron Technology		ICE Components	
ETSI		iC-Haus	
Ettinger		Illinois Capacitor	
Eurohm		ILSI America	
Euroquartz Ltd		Imo Precision Controls	
Everlight Everspin Technologies		Industrial FiberopticsInertial Sense	
Exar Corporation		Infineon	
Excelitas		Infinite Power Solutions	
Excellence Optoelectronics EX		Infomart	
Fagor Electronica		Innovasic	
Fairchild Imaging		Inolux	
Fairchild Semiconductor		Integrated Device Technology	
Fair-Rite		Integrated Silicon	
Fairview Microwave		Intel	
Faratronic		International Rectifier	
Fastron		Intersil	
Ferroxcube		Invac	
Finder		InvenSense	
Finisar		I-PEX	
First Sensor		IQD Frequency Products	
Fischer Elektronik		Ironwood Electronics	
Fox Electronics	FOX	ITG Electronics	
Foxconn Electronics	FOXCONN	ITT Cannon	ITT

IXYS	IXYS	MG Electronics	MGELECTRONICS
JALCO Co., Ltd		Micrel	
Japan Aviation Electronics	JAE	Micro Commercial	MICRO
Jauch Quartz GmbH	JAUCH	Microchip	MICROCHIP
Johanson		MicroCrystal	
JPC		Micron	
JQL Electronics		Micronas	
JRC		Micropac	
JSTKaweei Technology		MicroPower Direct MICROS	
KDS		Microsemi	
Kemet		MILL-MAX	
Keysight Technologies		Mini-Circuits	
Keystone Electronics		MiniRF	
Kindwin Opto Electronic		Minntronix	
King Core Electronics		Mirrorcle Technologies	
Kingbright		Mitsubishi Electric	
Kingstate Electronics		MMD	MMD
Kionix	KIONIX	Molex	
KitaGawa		Monolithic Power Systems	
Knitter-Switch		MORNSUN	
Knowles Electronics		Most Well Technology	
KOA Speer Electronics		Motocraft	
Kobiconn		Moxie	_
Kodenshi		MPE Garry	
KOTL	_	MS Kennedy	
KYCON		MtronPTI	
Kyocera		Multicomp	
Kyushu Dentsu		Murata	
Laird Lantronix		NDK Neltron Industrial	
Lattice Semiconductor		NetPower	
Leach		Neutrik USA	
Leader Tech		Newhaven Display	
Ledtronics		Nexperia	
Legacy Technologies		NIC Components	
Lelon		Nichia Corporation	
LEM		Nichicon	
LEMO		Nicomatic	
Leoco	LEOCO	Nippon Chemi-Con	
Lime Microsystems	LIME	NKK Switches	
Linear Technology		NorComp	NORCOMP
LINK-PP	LINKPP	Nordic	NORDIC
Linx	LINX	Nover	NOVER
Lite-On Optoelectronics		Nuvoton	
Littelfuse		NXP Semiconductors	
Lotes		ODU	
LS Mtron		OEP	
LSR		Ohmite	
Lumex		Omnetics	
Lumileds		OmniVision Technologies	
Luminus		OMRON	
Lyn-Tron		ON Semiconductor	
MAC8 MACOM		On Shore Technology Opto Diode	
Macronix		OSA Opto Light	
Maestro Wireless		Osram	
Mallory Sonalert Products		OUPIIN	
Marathon Special Products		PAN JIT International	
Marki Microwave		Panasonic	
Marktech		PANCON	
Marvell		PARA Light	
Maxim Integrated		Parallax	
MEAN WELL		Passive Plus	
MEC Switches		PCA Electronics	
Meder		PCI Express	
MegaChips	MEGACHIPS	PennEngineering	PENNENG
Memory Protection Devices	MPD	Peregrine Semiconductor	
Mercury Crystal		Pericom Semiconductor	
Meticom	METICOM	Phoenix Contact	
METZ Connect	METZ	Pickering	PICKERING

Pico Electronics	PICO	Semtech	SEMTECH
Piconics		Sena Technologies	
Picor	PICOR	Sensata Technologies/Airpax	
PIHER	PIHER	Sensata WELLS-CTI	
Plessey	PLESSEY	Sensirion	SENSIRION
Pletronics	PLETRONICS	Sensitron	SENSITRON
Polyshine	POLYSHINE	Sensor Electronic Technology	SETI
Positronic		Seoul Semiconductor	SEOULSEMI
Power Integrations	POWERINT	SGX Sensortech	SGXSENSORTECH
PPT Shenzhen Magnetic Technology		Sharp Microelectronics	
Preci-Dip		SIBA Fuses	
Presidio Components		Sierra Wireless	
Proant		Sigma Designs	SIGMA
Prolific	PROLIFIC	Signal Transformer	SIGNAL
Protek Devices	PROTEK	Silego Technology	
P-TEC	PTEC	Silergy	
PTR Messtechnik	PTRM	Silex Technology	
PUI Audio		Silicon Labs	
Pulse Electronics	PULSE	Silvertel	SILVERTEL
Purdy	PURDY	Singatron Enterprises	SINGATRON
Qorvo	QORVO	SITIME	SITIME
QT Brightek	QTBRIGHTEK	Siward	
Q-TECH	QTECH	SK hynix	SKHYNIX
Qualcomm	QUALCOMM	Skylab	SKYLAB
Qualtek Electronics		Skyworks Solutions	
Quectel	QUECTEL	SMEC	
Quickfilter Technologies	QUICKFILTER	Smiths Connectors	SMITHS
QuickLogic		SMK	SMK
Radiall		SMP Technology	SMPTECH
RAFI		Snaptron	
Rakon	RAKON	Soberton	
RALEC	RALEC	Solomon Systech	SOLOMONSYS
Ralink	RALINK	Song Chuan	
Raltron	RALTRON	Sonix Technology	SONIX
Rami Technology	RAMITECH	Souriau Connection Technology	
Ramtron	RAMTRON	Southwest Microwave	SOUTHWEST
Raytac	RAYTAC	Spansion	SPANSION
RCD Components	RCDCOMP	Sprague-Goodman	SPRAGUE
RDI	RDI	ST Microelectronics	ST
Realtek Semiconductor	REALTEKSEMI	Stackpole Electronics	STACKPOLE
RECOM Electronic	RECOM	Standex-Meder Electronics	STANDEX
Rectron	RECTRON	Stanley Electric	STANLEY
Redpine Signals	REDPINE	STAR MICRONICS	STAR
Renata Battaries	RENATA	STARCONN	STARCONN
Renco Electronics	RENCO	State of the Art	
Renesas Electronics	RENESAS	Stewart Connector	STEWART
RF Solutions	RFSOL	Sullins Connector Solutions	SULLINS
RFHIC	RFHIC	Sumida	SUMIDA
RFMD	RFMD	Sunex Digital Imaging Optics	SUNEX
Rhopoint Components	RHOPOINT	SunLED	
Richtek Technology	RICHTEK	Sunlord	SUNLORD
Ricoh Electronic Devices		Suotek	SUOTEK
Riedon	RIEDON	Surge Components	SURGECOMP
Rigado	RIGADO	Susumu	
RLC Electronics		Suyin Technologies	SUYIN
RLS	RLS	Switchcraft	
ROHM Semiconductor	ROHM	SYFER	SYFER
RS	RS	SynQor	SYNQOR
Rubycon	RUBYCON	Tadiran Batteries	
Samsung Electro-Mechanics	SAMSUNGEM	Tag Connect	
Samsung Semiconductor		Taicom	
Samtec		Taimag	TAIMAG
SanDisk	SANDISK	Tai-Saw Technology	
Sangshin	SANGSHIN	TaiTien Electric	
Sanken Electric		TAITRON	
Sanyo		Taiwan Semiconductor	
Schaffner		Taiyo Yuden	
Schurter		Talema Group	
SEGGER		Tamura	
Seiko Instruments		Taoglas	
Semitec		TDK	

TE Connectivity Tecate	
Tecate	TE
Tektronix	
Telit	TELIT
Tensility International	TENSILITY
Texas Instruments	TI
Therma-Flo	THERMAFLO
Thinking Electronics	THINKING
Titan Opto	TITANOPTO
Toko America	
Topline	
Torex Semiconductor	
Toshiba	
Traco	TRACO
Transko	TRANSKO
Triad Magnetics	TRIADMAGNETICS
Triad Semiconductor	
Trinamic Motion Control GmbH	TPINAMIC
TriQuint	IRIQUINI
TRP Connector	
TT Electronics	
Tusonix	TUSONIX
TXC Corporation	TXC
U-Blox	UBLOX
United Chemi-Con	UNITEDCC
UTAC Thai	UTACTHAL
VectorNav Technologies	
Vectron	
VEN	
Venkel	
VIA Labs	
Vicor	VICOR
Vishay	VISHAY
Visual Communications	VCC
Vitec Electronics	VITEC
Vitrohm	VITROHM
VLSI Solutions	
Volgen/Kaga Electronics	
Voltage Multipliers	VOLTAGEMULTI
Voltronics	VOLTRONICS
VPT Power	
VTI	
WAGO	
	WAGO
Walsin Technology	WAGO WALSIN
Walsin Technology Wamco	WAGO WALSIN WAMCO
Walsin Technology Wamco Weco	WAGOWALSINWAMCOWECO
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Walsin Technology	WAGO WALSIN WAMCO WECO WEENSEMI WEIDMULLER WIMA WINBOND WIZNET WOLFSON WORLDSEMI WPPRO WURTH XFMRS
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